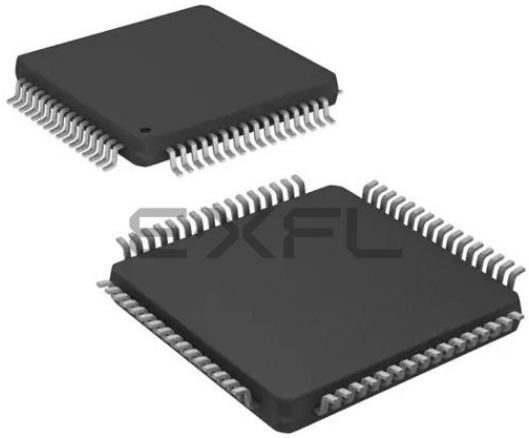

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128gp206-h-pt

3.5 Programmer's Model

The programmer's model for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X is shown in Figure 3-2. All registers in the programmer's model are memory mapped and can be manipulated directly by instructions. Table 3-1 lists a description of each register.

In addition to the registers contained in the programmer's model, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain control registers for Modulo Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only), Bit-Reversed Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only) and interrupts. These registers are described in subsequent sections of this document.

All registers associated with the programmer's model are memory mapped, as shown in Table 4-1.

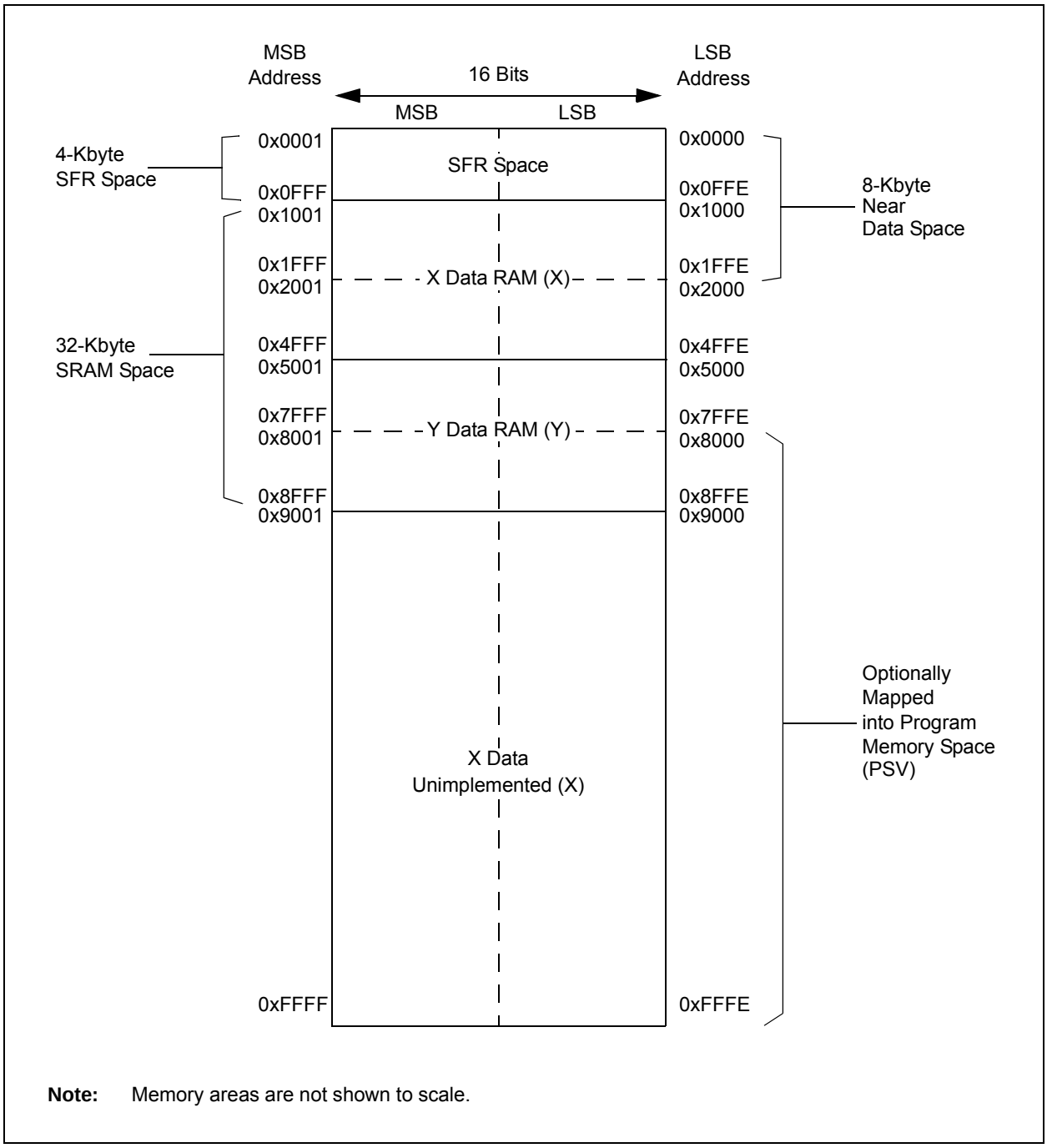
TABLE 3-1: PROGRAMMER'S MODEL REGISTER DESCRIPTIONS

Register(s) Name	Description
W0 through W15	Working Register Array
ACCA, ACCB	40-Bit DSP Accumulators
PC	23-Bit Program Counter
SR	ALU and DSP Engine STATUS Register
SPLIM	Stack Pointer Limit Value Register
TBLPAG	Table Memory Page Address Register
DSRPAG	Extended Data Space (EDS) Read Page Register
DSWPAG	Extended Data Space (EDS) Write Page Register
RCOUNT	REPEAT Loop Count Register
DCOUNT(1)	DO Loop Count Register
DOSTARTH(1,2), DOSTARTL(1,2)	DO Loop Start Address Register (High and Low)
DOENDH(1), DOENDL(1)	DO Loop End Address Register (High and Low)
CORCON	Contains DSP Engine, DO Loop Control and Trap Status bits

Note 1: This register is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: The DOSTARTH and DOSTARTL registers are read-only.

FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-11: PTG REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PTGCST	0AC0	PTGEN	—	PTGSIDL	PTGTOGL	—	PTGSWT	PTGSSEN	PTGIVIS	PTGSTRT	PTGWTO	—	—	—	—	PTGITM<1:0>		0000
PTGCON	0AC2	PTGCLK<2:0>			PTGDIV<4:0>					PTGPWD<3:0>				—	PTGWDT<2:0>			0000
PTGBTE	0AC4	ADCTS<4:1>				IC4TSS	IC3TSS	IC2TSS	IC1TSS	OC4CS	OC3CS	OC2CS	OC1CS	OC4TSS	OC3TSS	OC2TSS	OC1TSS	0000
PTGHOLD	0AC6	PTGHOLD<15:0>																0000
PTGT0LIM	0AC8	PTGT0LIM<15:0>																0000
PTGT1LIM	0ACA	PTGT1LIM<15:0>																0000
PTGSDLIM	0ACC	PTGSDLIM<15:0>																0000
PTGC0LIM	0ACE	PTGC0LIM<15:0>																0000
PTGC1LIM	0AD0	PTGC1LIM<15:0>																0000
PTGADJ	0AD2	PTGADJ<15:0>																0000
PTGL0	0AD4	PTGL0<15:0>																0000
PTGQPTR	0AD6	—	—	—	—	—	—	—	—	—	—	—	PTGQPTR<4:0>					0000
PTGQUE0	0AD8	STEP1<7:0>								STEP0<7:0>								0000
PTGQUE1	0ADA	STEP3<7:0>								STEP2<7:0>								0000
PTGQUE2	0ADC	STEP5<7:0>								STEP4<7:0>								0000
PTGQUE3	0ADE	STEP7<7:0>								STEP6<7:0>								0000
PTGQUE4	0AE0	STEP9<7:0>								STEP8<7:0>								0000
PTGQUE5	0AE2	STEP11<7:0>								STEP10<7:0>								0000
PTGQUE6	0AE4	STEP13<7:0>								STEP12<7:0>								0000
PTGQUE7	0AE6	STEP15<7:0>								STEP14<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-53: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	—	—	TRISA10	TRISA9	TRISA8	TRISA7	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	079F
PORTA	0E02	—	—	—	—	—	RA10	RA9	RA8	RA7	—	—	RA4	RA3	RA2	RA1	RA0	0000
LATA	0E04	—	—	—	—	—	LATA10	LATA9	LATA8	LATA7	—	—	LATA4	LATA3	LATA2	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	—	—	ODCA10	ODCA9	ODCA8	ODCA7	—	—	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	—	—	CNIEA10	CNIEA9	CNIEA8	CNIEA7	—	—	CNIEA4	CNIEA3	CNIEA2	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	—	—	CNPUA10	CNPUA9	CNPUA8	CNPUA7	—	—	CNPUA4	CNPUA3	CNPUA2	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	—	—	CNPDA10	CNPDA9	CNPDA8	CNPDA7	—	—	CNPDA4	CNPDA3	CNPDA2	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	—	—	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	0013

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-54: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-55: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	—	—	—	—	—	—	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF
PORTC	0E22	—	—	—	—	—	—	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATC	0E24	—	—	—	—	—	—	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	0E26	—	—	—	—	—	—	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000
CNENC	0E28	—	—	—	—	—	—	CNIEC9	CNIEC8	CNIEC7	CNIEC6	CNIEC5	CNIEC4	CNIEC3	CNIEC2	CNIEC1	CNIEC0	0000
CNPUC	0E2A	—	—	—	—	—	—	CNPUC9	CNPUC8	CNPUC7	CNPUC6	CNPUC5	CNPUC4	CNPUC3	CNPUC2	CNPUC1	CNPUC0	0000
CNPDC	0E2C	—	—	—	—	—	—	CNPDC9	CNPDC8	CNPDC7	CNPDC6	CNPDC5	CNPDC4	CNPDC3	CNPDC2	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	—	—	—	—	—	—	—	—	—	ANSC2	ANSC1	ANSC0	0007

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

7.3 Interrupt Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

7.3.1 KEY RESOURCES

- **"Interrupts"** (DS70600) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

7.4 Interrupt Control and Status Registers

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement the following registers for the interrupt controller:

- INTCON1
- INTCON2
- INTCON3
- INTCON4
- INTTREG

7.4.1 INTCON1 THROUGH INTCON4

Global interrupt control functions are controlled from INTCON1, INTCON2, INTCON3 and INTCON4.

INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS), as well as the control and status flags for the processor trap sources.

The INTCON2 register controls external interrupt request signal behavior and also contains the Global Interrupt Enable bit (GIE).

INTCON3 contains the status flags for the DMA and D0 stack overflow status trap sources.

The INTCON4 register contains the software generated hard trap status bit (SGHT).

7.4.2 IFSx

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

7.4.3 IECx

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.4.4 IPCx

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

7.4.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into the Vector Number bits (VECNUM<7:0>) and Interrupt Priority Level bits (ILR<3:0>) fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence as they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

7.4.6 STATUS/CONTROL REGISTERS

Although these registers are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. For more information on these registers refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user software can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-3 through Register 7-7 in the following pages.

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator"** (DS70580) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

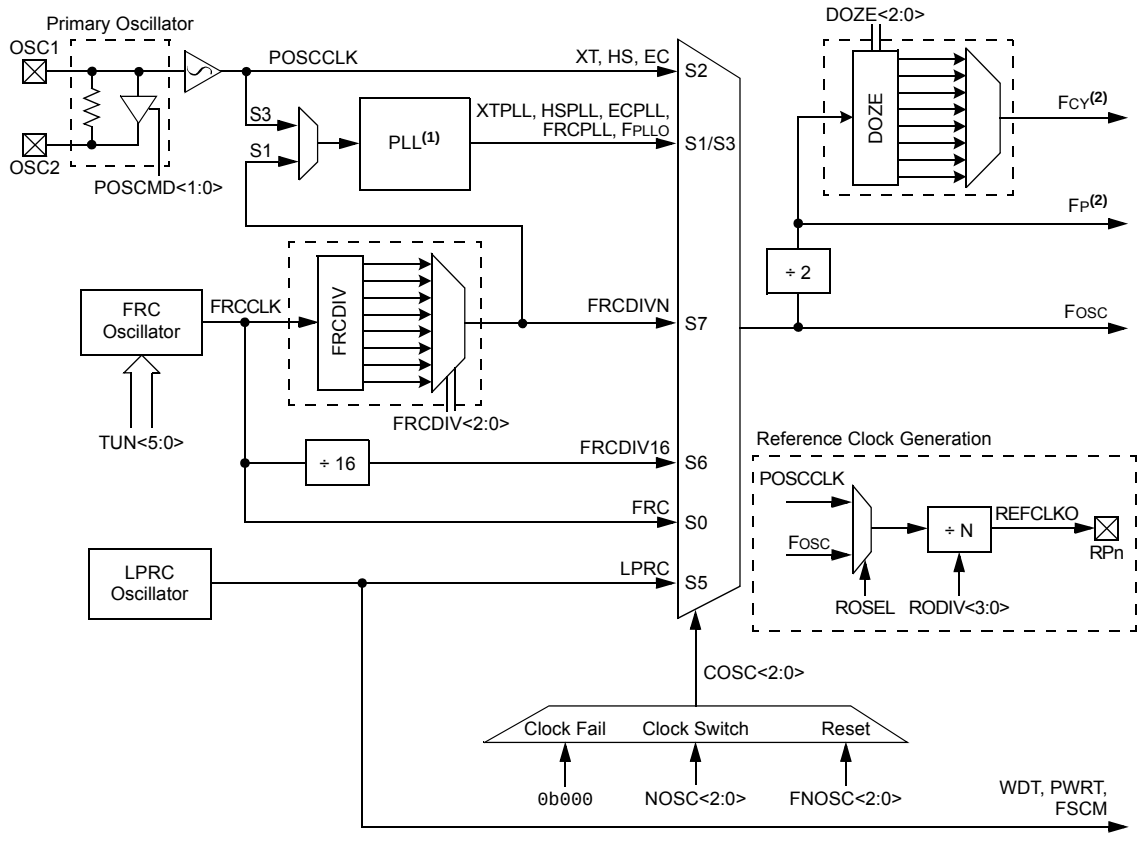
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a doze ratio of 1:2 or lower.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1) (CONTINUED)

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit(3)
- 1 = FSCM has detected clock failure
- 0 = FSCM has not detected clock failure

bit 2-1 **Unimplemented:** Read as '0'

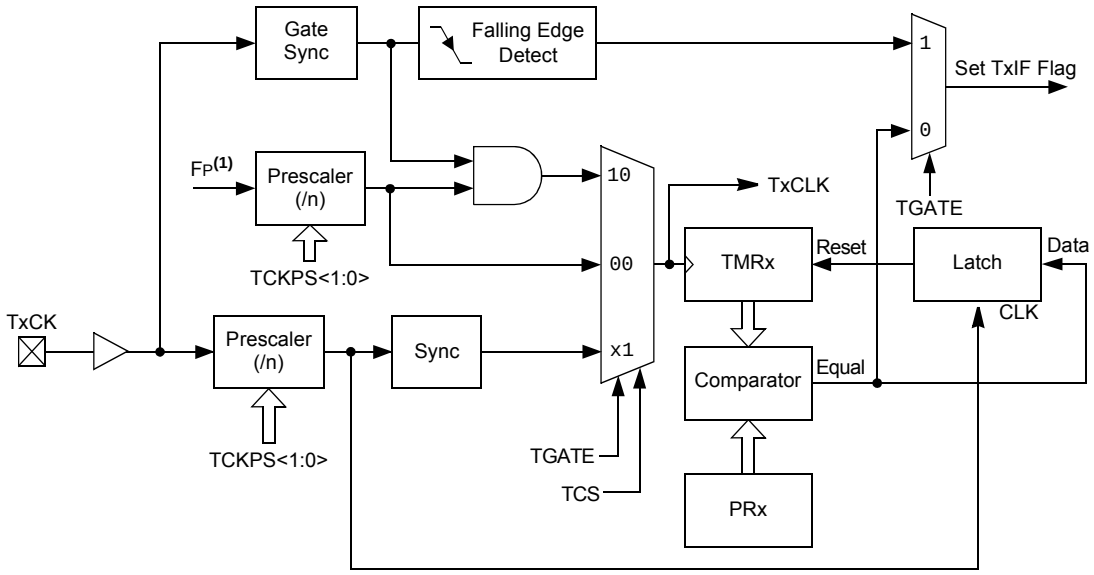
bit 0 **OSWEN:** Oscillator Switch Enable bit
- 1 = Requests oscillator switch to selection specified by the NOSC<2:0> bits
- 0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"* (available from the Microchip web site) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

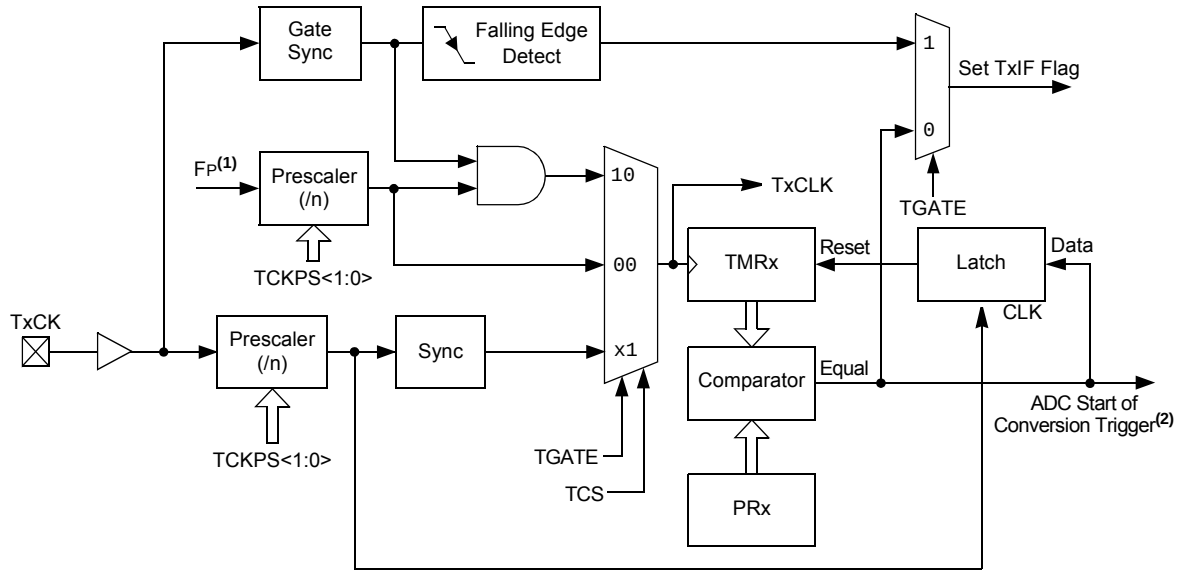
3: This bit should only be cleared in software. Setting the bit in software (= 1) will have the same effect as an actual oscillator failure and trigger an oscillator failure trap.

FIGURE 13-1: TYPE B TIMER BLOCK DIAGRAM (x = 2 AND 4)



Note 1: FP is the peripheral clock.

FIGURE 13-2: TYPE C TIMER BLOCK DIAGRAM (x = 3 AND 5)



Note 1: FP is the peripheral clock.
2: The ADC trigger is available on TMR3 and TMR5 only.

19.2 I²C Control Registers

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN(1)	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I²C™ pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I²C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception. Hardware is clear at the end of every slave data byte reception.
If STREN = 0:
Bit is R/S (i.e., software can only write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit(1)
1 = IPMI mode is enabled; all addresses are Acknowledged
0 = IPMI mode disabled

bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specification
0 = Disables SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I²C slave)
1 = Enables interrupt when a general call address is received in I2CxRSR (module is enabled for reception)
0 = General call address disabled

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

REGISTER 21-16: CxRXFnSID: ECANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Message address bit, SIDx, must be '1' to match filter
0 = Message address bit, SIDx, must be '0' to match filter

bit 4 **Unimplemented:** Read as '0'

bit 3 **EXIDE:** Extended Identifier Enable bit
If MIDE = 1:
1 = Matches only messages with Extended Identifier addresses
0 = Matches only messages with Standard Identifier addresses
If MIDE = 0:
Ignores EXIDE bit.

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Message address bit, EIDx, must be '1' to match filter
0 = Message address bit, EIDx, must be '0' to match filter

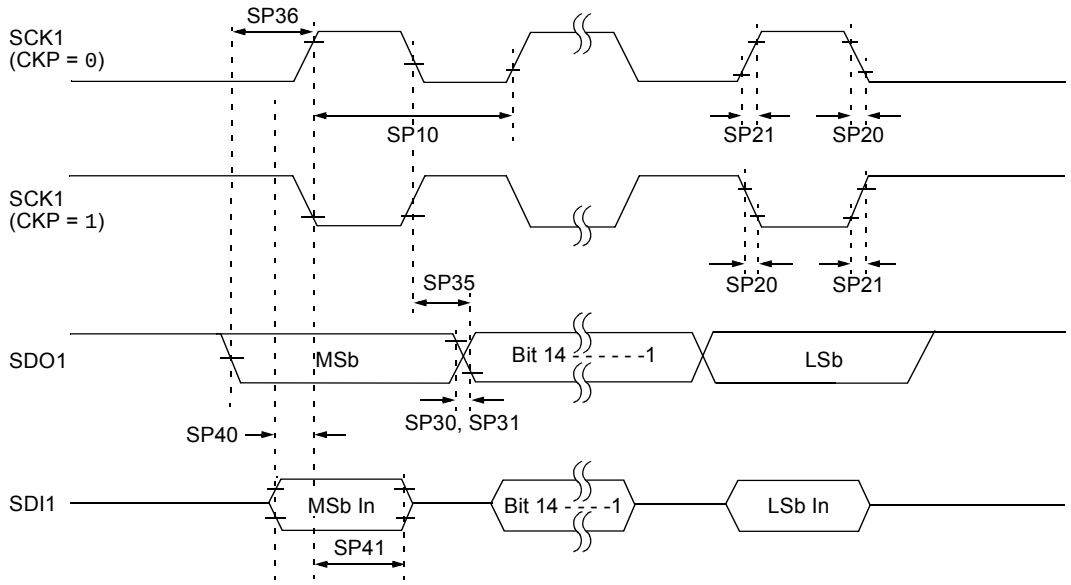
TABLE 27-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Description
WDTPRE	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
WDTWIN<1:0>	Watchdog Window Select bits 11 = WDT window is 25% of WDT period 10 = WDT window is 37.5% of WDT period 01 = WDT window is 50% of WDT period 00 = WDT window is 75% of WDT period
ALTI2C1	Alternate I2C1 pin 1 = I2C1 is mapped to the SDA1/SCL1 pins 0 = I2C1 is mapped to the ASDA1/ASCL1 pins
ALTI2C2	Alternate I2C2 pin 1 = I2C2 is mapped to the SDA2/SCL2 pins 0 = I2C2 is mapped to the ASDA2/ASCL2 pins
JTAGEN(2)	JTAG Enable bit 1 = JTAG is enabled 0 = JTAG is disabled
ICS<1:0>	ICD Communication Channel Select bits 11 = Communicate on PGEC1 and PGED1 10 = Communicate on PGEC2 and PGED2 01 = Communicate on PGEC3 and PGED3 00 = Reserved, do not use

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

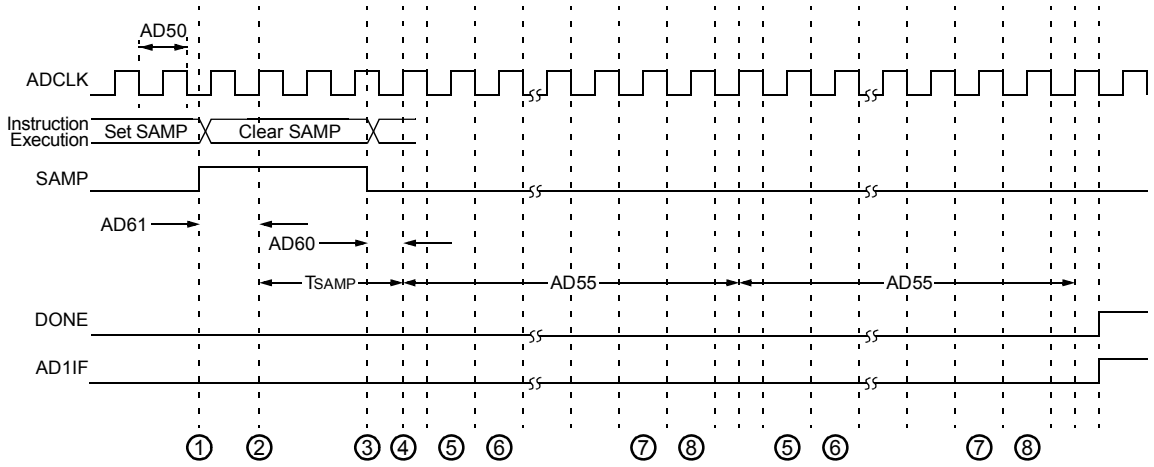
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



1 – Software sets AD1CON1. SAMP to start sampling.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

3 – Software clears AD1CON1. SAMP to start conversion.

4 – Sampling ends, conversion sequence starts.

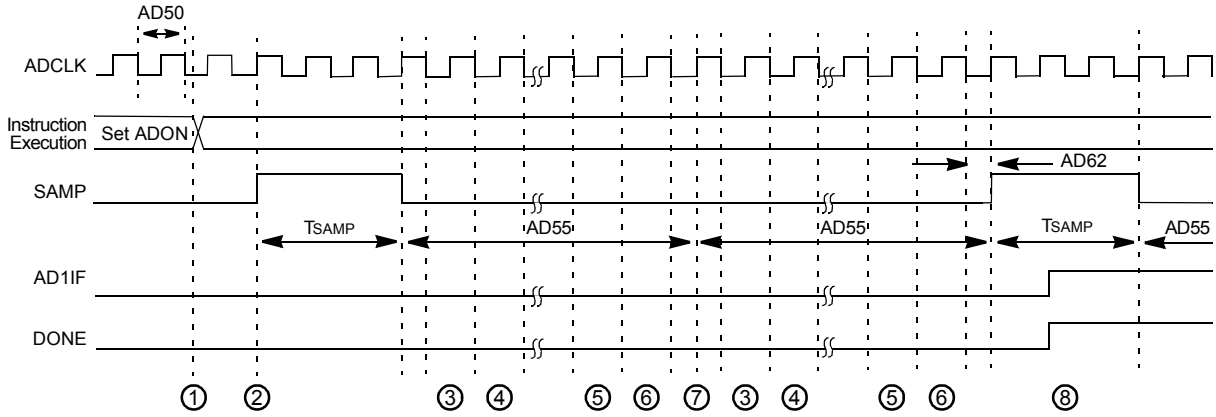
5 – Convert bit 9.

6 – Convert bit 8.

7 – Convert bit 0.

8 – One TAD for end of conversion.

FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



1 – Software sets AD1CON1. ADON to start AD operation.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

3 – Convert bit 9.

4 – Convert bit 8.

5 – Convert bit 0.

6 – One TAD for end of conversion.

7 – Begin conversion of next channel.

8 – Sample for time specified by SAMC<4:0>.

31.1 High-Temperature DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
HDC5	3.0 to 3.6V(1)	-40°C to +150°C	40

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules, such as the ADC, may have degraded performance. Device functionality is tested but not characterized.

TABLE 31-2: THERMAL OPERATING CONDITIONS

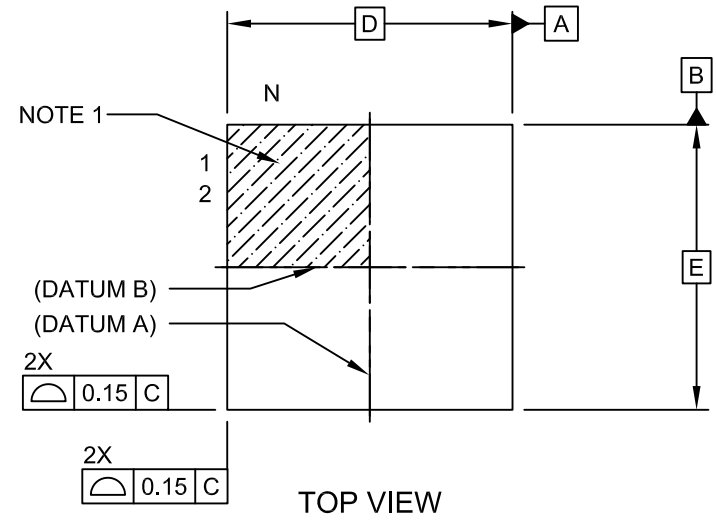
Rating	Symbol	Min	Typ	Max	Unit
High-Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 31-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

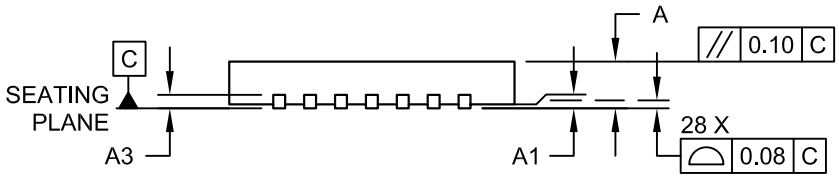
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	**Supply Voltage**						
	VDD	—	3.0	3.3	3.6	V	-40°C to +150°C

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

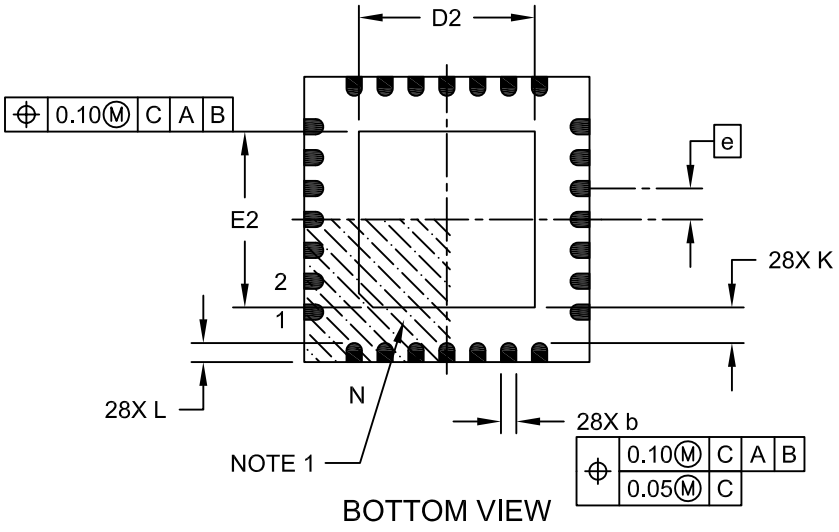
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

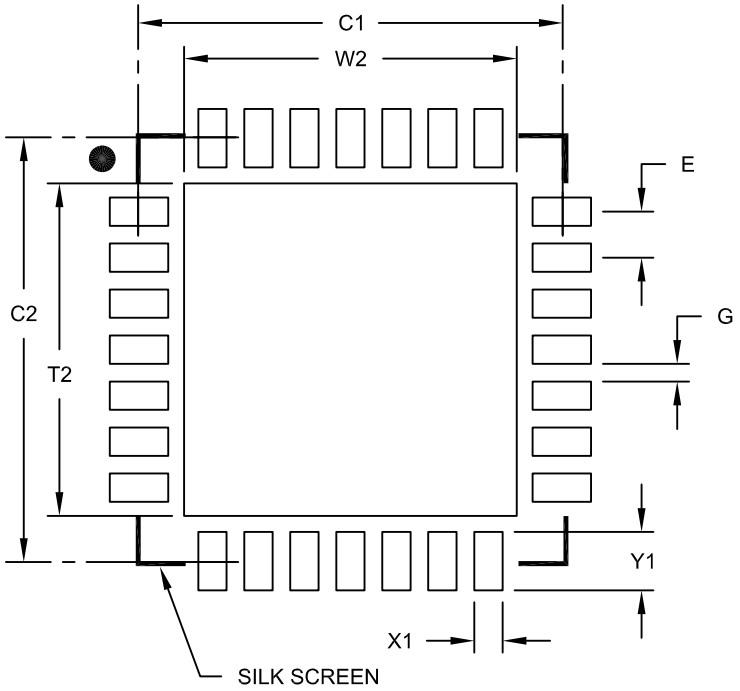


BOTTOM VIEW

Microchip Technology Drawing C04-124C Sheet 1 of 2

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings(1). Removed Parameter DC18 (VCORE) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated Note 1 in the DC Characteristics: Operating Current (IDD) (see Table 30-6). Updated Note 1 in the DC Characteristics: Idle Current (IIDLE) (see Table 30-7). Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (IPD) (see Table 30-8). Updated Note 1 in the DC Characteristics: Doze Current (IDOZE) (see Table 30-9). Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12). Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated Internal FRC Accuracy Parameter F20a (see Table 30-21). Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 "Packaging Information"	Updated packages by replacing references of VLAP with TLA.
"Product Identification System"	Changed VLAP to TLA.

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics" (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).

Revision F (November 2012)

Removed “Preliminary” from data sheet footer.

Revision G (March 2013)

This revision includes the following global changes:

- changes “$\overline{\text{FLTx}}$” pin function to “FLTx” on all occurrences
- adds **Section 31.0 “High-Temperature Electrical Characteristics”** for high-temperature (+150°C) data

This revision also includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-5.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Changes internal oscillator specification to 1.0% • Changes I/O sink/source values to 12 mA or 6 mA • Corrects 44-pin VTLA pin diagram (pin 32 now shows as 5V tolerant)
Section 4.0 “Memory Organization”	• Deletes references to Configuration Shadow registers • Corrects the spelling of the JTAGIP and PTGWDTIP bits throughout • Corrects the Reset value of all IOCON registers as C000h • Adds footnote to Table 4-42 to indicate the absence of Comparator 3 in 28-pin devices
Section 6.0 “Resets”	• Removes references to cold and warm Resets, and clarifies the initial configuration of the device clock source on all Resets
Section 7.0 “Interrupt Controller”	• Corrects the definition of GIE as “Global Interrupt Enable” (not “General”)
Section 9.0 “Oscillator Configuration”	• Clarifies the behavior of the CF bit when cleared in software • Removes POR behavior footnotes from all control registers • Corrects the tuning range of the TUN<5:0> bits in Register 9-4 to an overall range ±1.5%
Section 13.0 “Timer2/3 and Timer4/5”	• Clarifies the presence of the ADC Trigger in 16-bit Timer3 and Timer5, as well as the 32-bit timers
Section 15.0 “Output Compare”	• Corrects the first trigger source for SYNCSEL<4:0> (OCxCON2<4:0>) as OCxRS match
Section 16.0 “High-Speed PWM Module”	• Clarifies the source of the PWM interrupts in Figure 16-1 • Corrects the Reset states of IOCONx<15:14> in Register 16-13 as ‘11’
Section 17.0 “Quadrature Encoder Interface (QEI) Module”	• Clarifies the operation of the IMV<1:0> bits (QEICON<9:8>) with updated text and additional notes • Corrects the first prescaler value for QFVDIV<2:0> (QEI1OC<13:11>), now 1:128
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Adds note to Figure 23-1 that Op Amp 3 is not available in 28-pin devices • Changes “sample clock” to “sample trigger” in AD1CON1 (Register 23-1) • Clarifies footnotes on op amp usage in Registers 23-5 and 23-6
Section 25.0 “Op Amp/ Comparator Module”	• Adds Note text to indicate that Comparator 3 is unavailable in 28-pin devices • Splits Figure 25-1 into two figures for clearer presentation (Figure 25-1 for Op amp/ Comparators 1 through 3, Figure 25-2 for Comparator 4). Subsequent figures are renumbered accordingly. • Corrects reference description in xxxxx (now (AV_{DD} + AV_{SS})/2) • Changes CMSTAT<15> in Register 25-1 to “PSIDL”
Section 27.0 “Special Features”	• Corrects the addresses of all Configuration bytes for 512 Kbyte devices

NOTES: